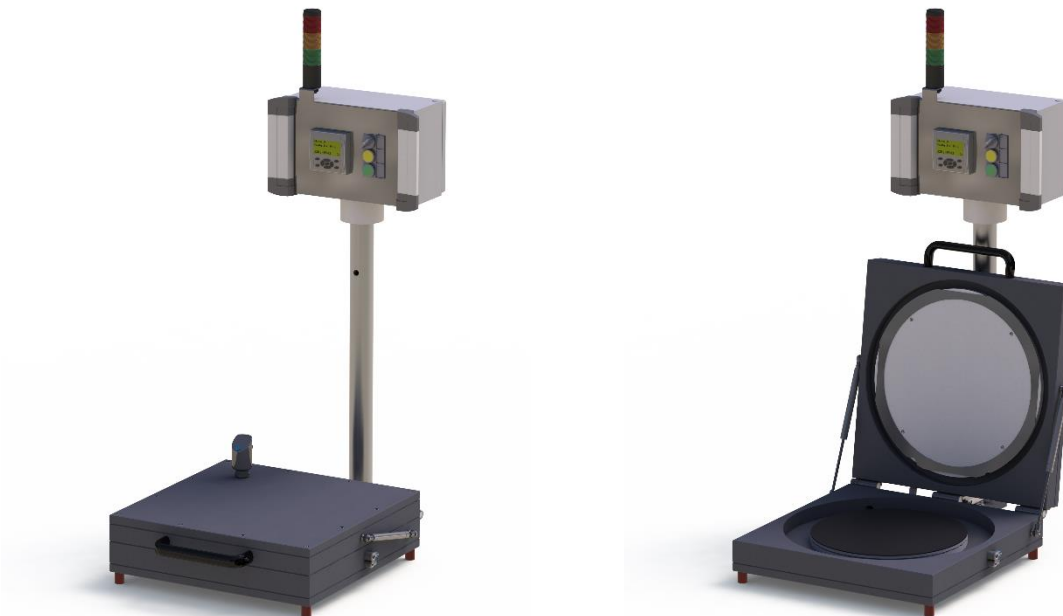


Semi-Automatic Heated Vacuum Wafer Mounter V-200H



POWATEC's V-200H heated Wafer Mounter is a highly specialized semi-automatic device for highest requirements in adhesion results of 200mm wafers or substrates onto a 8" frame mounted thermal film. It is mostly used in advanced research and development departments or series production of large companies. The personnel can achieve a throughput of up to 40 mounts per hour with minimal instruction. The strength of the V-200H lies in:

- The mounting of structured substrates (e.g. optical lenses) or bumped wafers on thermal film for structures of up to 170 μ
- The highly reproducible top-quality results
- Highest requirements for **homogeneous and concentric lamination** of flat wafers or substrates
- Controlled, highly reproducible and **minimal force exertion** onto the wafer or substrate
- Requirements on accurate and reproducible **temperature control**

POWATEC can customize the modular V-200H for your process requirements depending on the structure and geometry of the substrate as well as the thermal behavior of the film.

The extremely short set-up times, low operating costs, slim dimensions and the qualitatively outstanding and reproducible end-results are proven with years of experience and operation of the V200-H. Optionally, the V-200H can be equipped with cooling plates in order to guarantee necessary safety standards.

Product Features

- 80-100 seconds per mount
- Vacuum performance of 1-3 mbar absolute (-1 bar)
- Automatic process consists of vacuum generation, temperature control and controlled mounting sequence
- Adjustable mounting speed
- Adjustable time to preheat the wafer/substrate and film before mounting
- Display of mounting vacuum
- Display of heating temperature
- Table-top device
- Applicable for clear room application
- Product safety with cooling plate (option)

Unique Selling Proposition

- Mounting of thermal film on structured substrates (e.g. optical lenses) or bumped wafers up to 170µ structure
- Highly reproducible top-quality results
- Highest requirements for homogeneous and concentric lamination of flat wafers or substrates
- Controlled, highly re-producible and minimal force exertion onto the wafer or substrate
- Minimal maintenance (< 100 USD per year)

Chamber Dimensions & Mechanical Specification

Wafer-size:	up to 200 mm
Frame-size:	8" (OD 276 mm)
Frame Type:	Disco and K&S, Steel Material only
Width:	380 mm
Height:	775 mm
Depth:	640 mm
Weight:	40.4 kg

Cooling Equipment Specification

Cooling medium:	Water
Inlet type:	Ø 8 mm
Outlet type:	Ø 8 mm

Electrical Specification

Main power		110-240 VAC, 50/60 Hz
Power supply for control unit	Input	85-240 VAC
	Output	24 VDC/1.5A
	Power	max. 25 W
Power supply for heat controller	Input	230 VAC
	Output	42 VAC
	Power	2x 215 W

Pneumatic Specification

Required vacuum	8 mbar absolute
Vacuum connection	Festo PUN-8, Ø8 mm
Required air pressure	4-6 bar
Pressure connection	Festo PUN-6, Ø6 mm

Accessory



Vacuum-Pump

0.55KW, 220-240V, 50/60 Hz
 Comes with active carbon filter and exhaust particle remover designed from POWATEC for clean room application

Conformity

Build according to IEC 204-1
 CE marking

Related Products from POWATEC



Manual Wafer Mounter P-200

Mounting of up to 200mm Wafer onto 8" Film Frame



UV Flash Curing System UF-300

Curing of up to 300mm Wafer onto 300mm Film Frame



Vacuum Wafer Mounter V-200

Mounting of up to 200mm Wafer onto 8" Film Frame



Wafer Frame Magazine

200mm Wafer onto 8" Film Frame, 25 slots